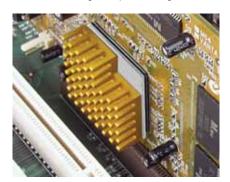
Bond-Ply® 100

Thermally Conductive, Fiberglass Reinforced Pressure Sensitive Adhesive Tape

Features and Benefits

- Thermal impedance: 0.52°C-in²/W (@50 psi)
- High bond strength to a variety of surfaces
- Double-sided, pressure sensitive adhesive tape
- High performance, thermally conductive acrylic adhesive
- Can be used instead of heat-cure adhesive, screw mounting or clip mounting



Typical Applications Include:

- Mount heat sink onto BGA graphic processor or drive processor
- Mount heat spreader onto power converter PCB or onto motor control PCB

Configurations Available:

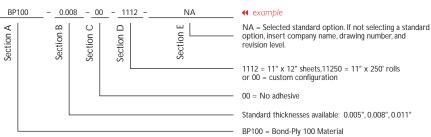
• Sheet form, roll form and die-cut parts

Shelf Life: The double-sided, pressure sensitive adhesive used in Bond-Ply products requires the use of dual liners to protect the surfaces from contaminants. Bergquist recommends a 6-month shelf life at a maximum continuous storage temperature of 35°C or 3-month shelf life at a maximum continuous storage temperature of 45°C, for maintenance of controlled adhesion to the liner. The shelf life of the Bond-Ply material, without consideration of liner adhesion (which is often not critical for manual assembly processing), is recommended at 12 months from date of manufacture at a maximum continuous storage temperature of 60°C.

TYPICAL PROPERTIES OF BOND-PLY 100						
PROPERTY	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	White		White		Visual	
Reinforcement Carrier	Fiberglass		Fiberglass		_	
Thickness (inch) / (mm)	0.005, 0.008, 0.011		0.127, 0.203, 0.279		ASTM D374	
Temp. Resistance, 30 sec. (°F) / (°C)	392		200		_	
Elongation (%45° to Warp & Fill)	70		70		ASTM D412	
Tensile Strength (psi) / (MPa)	900		6		ASTM D412	
CTE (ppm)	325		325		ASTM D3386	
Glass Transition (°F) / (°C)	-22		-30		ASTM 1356	
Continuous Use Temp (°F) / (°C)	-22 to 248		-30 to 120		_	
ADHESION						
Lap Shear @ RT (psi) / (MPa)	100		0.7		ASTM D1002	
Lap Shear after 5 hr @ 100°C	200		1.4		ASTM D1002	
Lap Shear after 2 min @ 200°C	200		1.4		ASTM D1002	
Static Dead Weight Shear (°F) / (°C)	302		150		PSTC#7	
ELECTRICAL			VALUE		TEST METHOD	
Dielectric Breakdown Voltage - 0.005" (Vac)			3000		ASTM D149	
Dielectric Breakdown Voltage - 0.008" (Vac)			6000		ASTM D149	
Dielectric Breakdown Voltage - 0.011" (Vac)			8500		ASTM D149	
Flame Rating			V-O		U.L.94	
THERMAL						
Thermal Conductivity (W/m-K)			0.8		ASTM D5470	
THERMAL PERFORMANCE vs PRESSURE						
Initial Assembly Pressure (psi for 5 seconds)		10	25	50	100	200
TO-220 Thermal Performance (°C/W) 0.005"		5.17	4.87	4.49	4.18	4.10
TO-220 Thermal Performance (°C/W) 0.008"		5.40	5.35	5.28	5.22	5.20
TO-220 Thermal Performance (°C/W) 0.011"		6.39	6.51	6.51	6.50	6.40
Thermal Impedance (°C-in²/W) (0.56	0.84	0.52	0.50	0.50	
Thermal Impedance (°C-in²/W) 0.008" (1)		0.82	0.80	0.78	0.77	0.75
Thermal Impedance (°C-in²/W)	1.03	1.02	1.01	1.00	0.99	
1) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These						

1) The AST MODAL INCIDENT WAS USED. THE RECORDED VALUES INCLUDES INTERFACIAL INERTIAL RESIDENCE. THESE values are provided for reference only Actual application performance is directly related to the surface roughness, flatness and pressure applied.

Building a Part Number



Note: To build a part number, visit our website at www.bergquistcompany.com.

Bond-Ply®: U.S. Patent 5,090,484 and others.



www.bergquistcompany.com

Standard Options